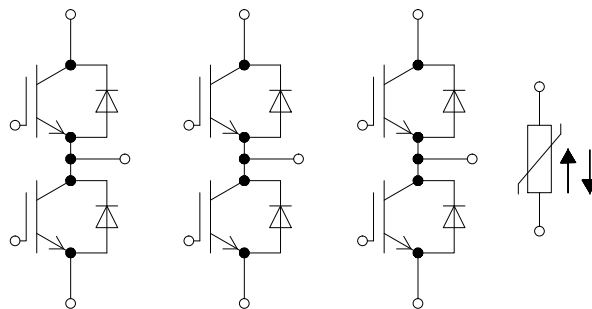


EconoPACK™+ Modul mit Trench/Feldstopp IGBT4 und Emitter Controlled 3 Diode und PressFIT / bereits aufgetragenem Thermal Interface Material

EconoPACK™+ module with Trench/Fieldstop IGBT4 and Emitter Controlled 3 diode and PressFIT / pre-applied Thermal Interface Material



$V_{CES} = 1700V$   
 $I_{C\ nom} = 450A / I_{CRM} = 900A$

### Typische Anwendungen

- Hilfsumrichter
- Hochleistungsumrichter
- Motorantriebe
- Windgeneratoren

### Typical Applications

- Auxiliary inverters
- High power converters
- Motor drives
- Wind turbines

### Elektrische Eigenschaften

- Hohe Kurzschlussrobustheit
- Hohe Stoßstromfestigkeit
- Sehr große Robustheit
- $T_{vj\ op} = 150^{\circ}C$
- Trench IGBT 4

### Electrical Features

- High short-circuit capability
- High surge current capability
- Unbeatable robustness
- $T_{vj\ op} = 150^{\circ}C$
- Trench IGBT 4

### Mechanische Eigenschaften

- Hohe mechanische Robustheit
- Integrierter NTC Temperatur Sensor
- Isolierte Bodenplatte
- PressFIT Verbindungstechnik
- RoHS konform
- Thermisches Interface Material bereits aufgetragen

### Mechanical Features

- High mechanical robustness
- Integrated NTC temperature sensor
- Isolated base plate
- PressFIT contact technology
- RoHS compliant
- Pre-applied Thermal Interface Material

### Module Label Code

#### Barcode Code 128



#### DMX - Code



#### Content of the Code

Content of the Code	Digit
Module Serial Number	1 - 5
Module Material Number	6 - 11
Production Order Number	12 - 19
Datecode (Production Year)	20 - 21
Datecode (Production Week)	22 - 23

prepared by: SM	date of publication: 2016-07-29	
approved by: KV	revision: V3.0	UL approved (E83335)



**IGBT, Wechselrichter / IGBT, Inverter**  
**Höchstzulässige Werte / Maximum Rated Values**

Kollektor-Emitter-Sperrspannung Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	$V_{CES}$	1700	V
Kollektor-Dauergleichstrom Continuous DC collector current	$T_H = 55^{\circ}\text{C}, T_{vj\text{ max}} = 175^{\circ}\text{C}$	$I_{C\text{ nom}}$	450	A
Periodischer Kollektor-Spitzenstrom Repetitive peak collector current	$t_P = 1\text{ ms}$	$I_{CRM}$	900	A
Gate-Emitter-Spitzenspannung Gate-emitter peak voltage		$V_{GES}$	+/-20	V

**Charakteristische Werte / Characteristic Values**

			min.	typ.	max.		
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage	$I_C = 450\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 450\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 450\text{ A}, V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{ sat}}$	1,95 2,35 2,45	2,30	V V V	
Gate-Schwellenspannung Gate threshold voltage	$I_C = 18,0\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		$V_{GEth}$	5,20	5,80	6,40	V
Gateladung Gate charge	$V_{GE} = -15\text{ V} \dots +15\text{ V}$		$Q_G$	4,60			$\mu\text{C}$
Interner Gatewiderstand Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		$R_{Gint}$	1,7			$\Omega$
Eingangskapazität Input capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		$C_{ies}$	36,0			nF
Rückwirkungskapazität Reverse transfer capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		$C_{res}$	1,15			nF
Kollektor-Emitter-Reststrom Collector-emitter cut-off current	$V_{CE} = 1700\text{ V}, V_{GE} = 0\text{ V}, T_{vj} = 25^{\circ}\text{C}$		$I_{CES}$			3,0	mA
Gate-Emitter-Reststrom Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		$I_{GES}$			400	nA
Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load	$I_C = 450\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 3,3\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{don}$	0,19 0,22 0,22			$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Anstiegszeit, induktive Last Rise time, inductive load	$I_C = 450\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 3,3\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_r$	0,09 0,09 0,09			$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load	$I_C = 450\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 3,3\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{doff}$	0,75 0,89 0,93			$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Fallzeit, induktive Last Fall time, inductive load	$I_C = 450\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 3,3\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_f$	0,11 0,16 0,17			$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Einschaltverlustenergie pro Puls Turn-on energy loss per pulse	$I_C = 450\text{ A}, V_{CE} = 900\text{ V}, L_S = 35\text{ nH}$ $V_{GE} = \pm 15\text{ V}, di/dt = 4800\text{ A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $R_{Gon} = 3,3\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{on}$	130 165 175			mJ mJ mJ
Abschaltverlustenergie pro Puls Turn-off energy loss per pulse	$I_C = 450\text{ A}, V_{CE} = 900\text{ V}, L_S = 35\text{ nH}$ $V_{GE} = \pm 15\text{ V}, du/dt = 3100\text{ V}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $R_{Goff} = 3,3\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{off}$	81,5 135 155			mJ mJ mJ
Kurzschlußverhalten SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 1000\text{ V}$ $V_{CEmax} = V_{CES} - L_{SCE} \cdot di/dt$ $t_P \leq 10\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$		$I_{SC}$	1800			A
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro IGBT / per IGBT valid with IFX pre-applied thermal interface material		$R_{thJH}$			0,0912	K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{ op}}$	-40		150	$^{\circ}\text{C}$

prepared by: SM	date of publication: 2016-07-29
approved by: KV	revision: V3.0



**Diode, Wechselrichter / Diode, Inverter**

**Höchstzulässige Werte / Maximum Rated Values**

Periodische Spitzensperrspannung Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	$V_{RRM}$	1700	V
Dauergleichstrom Continuous DC forward current		$I_F$	450	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_P = 1\text{ ms}$	$I_{FRM}$	900	A
Grenzlastintegral $I^2t$ - value	$V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	$I^2t$	30000 27500	$\text{A}^2\text{s}$ $\text{A}^2\text{s}$

**Charakteristische Werte / Characteristic Values**

			min.	typ.	max.	
Durchlassspannung Forward voltage	$I_F = 450\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 450\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 450\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_F$	1,80 1,90 1,95	2,20	V V V
Rückstromspitze Peak reverse recovery current	$I_F = 450\text{ A}, -di_F/dt = 4800\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$I_{RM}$	425 525 550		A A A
Sperrverzögerungsladung Recovered charge	$I_F = 450\text{ A}, -di_F/dt = 4800\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$Q_r$	105 185 205		$\mu\text{C}$ $\mu\text{C}$ $\mu\text{C}$
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 450\text{ A}, -di_F/dt = 4800\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{rec}$	52,0 105 120		mJ mJ mJ
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro Diode / per diode valid with IFX pre-applied thermal interface material		$R_{thJH}$		0,157	K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{ op}}$	-40	150	$^{\circ}\text{C}$

**NTC-Widerstand / NTC-Thermistor**

**Charakteristische Werte / Characteristic Values**

			min.	typ.	max.	
Nennwiderstand Rated resistance	$T_{NTC} = 25^{\circ}\text{C}$		$R_{25}$	5,00		k $\Omega$
Abweichung von R100 Deviation of R100	$T_{NTC} = 100^{\circ}\text{C}, R_{100} = 493\ \Omega$		$\Delta R/R$	-5	5	%
Verlustleistung Power dissipation	$T_{NTC} = 25^{\circ}\text{C}$		$P_{25}$		20,0	mW
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15\text{ K}))]$		$B_{25/50}$	3375		K
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15\text{ K}))]$		$B_{25/80}$	3411		K
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15\text{ K}))]$		$B_{25/100}$	3433		K

Angaben gemäß gültiger Application Note.  
Specification according to the valid application note.

prepared by: SM	date of publication: 2016-07-29
approved by: KV	revision: V3.0



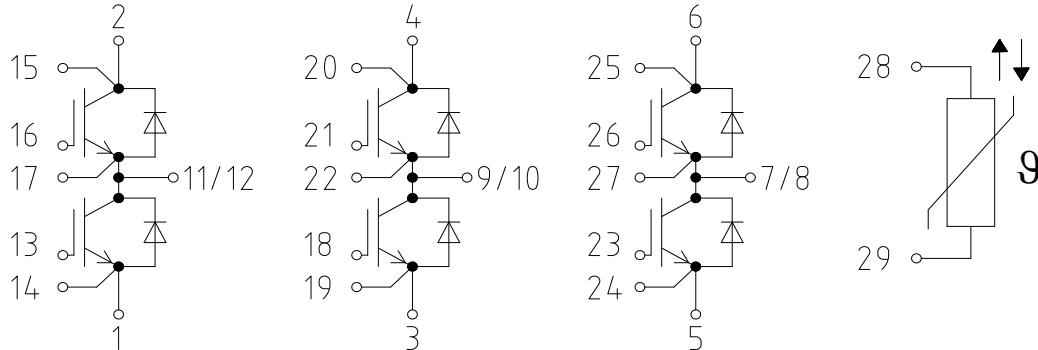
**Modul / Module**

Isolations-Prüfspannung Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	V <sub>ISOL</sub>	3,4		kV
Material Modulgrundplatte Material of module baseplate			Cu		
Innere Isolation Internal isolation	Basisisolierung (Schutzklasse 1, EN61140) basic insulation (class 1, IEC 61140)		Al <sub>2</sub> O <sub>3</sub>		
Kriechstrecke Creepage distance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		18,5 12,6		mm
Luftstrecke Clearance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		16,0 10,0		mm
Vergleichszahl der Kriechwegbildung Comperative tracking index		CTI	> 200		
			min.	typ.	max.
Modulstreuintduktivität Stray inductance module		L <sub>sCE</sub>		20	nH
Modulleitungswiderstand, Anschlüsse - Chip Module lead resistance, terminals - chip	T <sub>H</sub> = 25°C, pro Schalter / per switch	R <sub>CC+EE'</sub>		1,10	mΩ
Lagertemperatur Storage temperature		T <sub>stg</sub>	-40		125 °C
Höchstzulässige Bodenplattenbetriebstemperatur Maximum baseplate operation temperature		T <sub>BPmax</sub>			125 °C
Anzugsdrehmoment f. Modulmontage Mounting torque for modul mounting	Schraube M5 - Montage gem. gültiger Applikationsschrift Screw M5 - Mounting according to valid application note	M	3,00		6,00 Nm
Anzugsdrehmoment f. elektr. Anschlüsse Terminal connection torque	Schraube M6 - Montage gem. gültiger Applikationsschrift Screw M6 - Mounting according to valid application note	M	3,0	-	6,0 Nm
Gewicht Weight		G		924	g

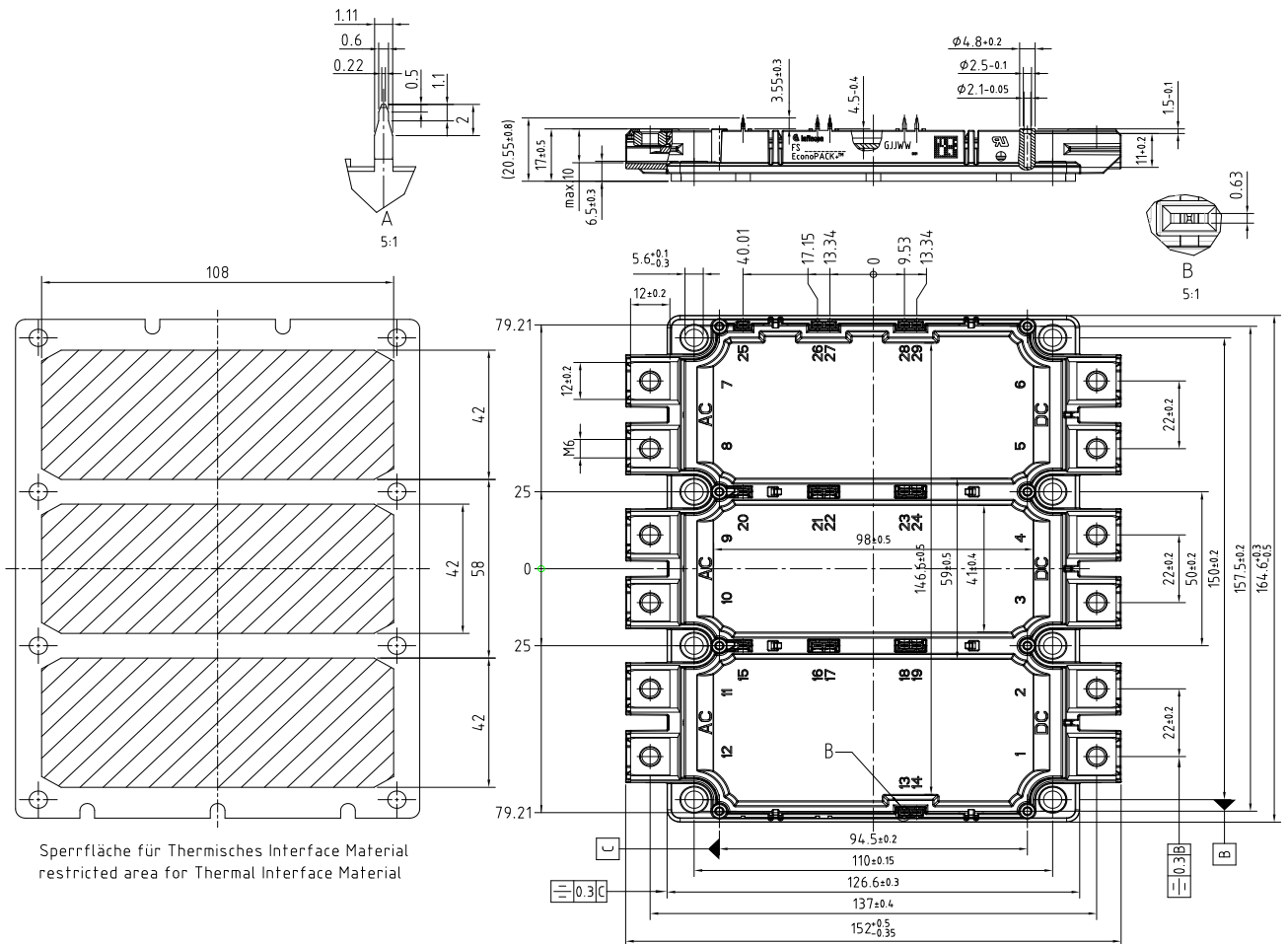
Lagerung und Transport von Modulen mit TIM => siehe AN2012-07  
Storage and shipment of modules with TIM => see AN2012-07

prepared by: SM	date of publication: 2016-07-29
approved by: KV	revision: V3.0

Schaltplan / Circuit diagram



Gehäuseabmessungen / Package outlines



prepared by: SM	date of publication: 2016-07-29
approved by: KV	revision: V3.0